

LISTING OF THE CLAIMS

This listing of claims, amended as indicated below, will replace all prior versions, and listings, of claims in the application

1. (Currently Amended) A method for processing a plurality of leadframe items to form IC packages an integrated circuit package, each of the leadframe items comprising an integrated circuit IC carried by a suitable leadframe, the leadframe items being of two or more types, the method including comprising the steps of:

receiving each of the two or more types of leadframe items along a respective input paths path;
moving at least two a plurality of holders corresponding in number to the number of integrated circuits to be processed alternately between a processing region and a respective leadframe item reception position [[;]] on a respective input path such that each of the holders moving moves to the processing region and at a time when the other of the holders /50, 60/ moves to its respective reception position; the reception positions being on respective ones of the input paths;

each of the holders receiving transferring the leadframe items of the respective type from the their respective input path paths to each respective ones of the holders at the respective reception position positions; and

delivering them the leadframe items to the processing region; and

at the processing region, sending the leadframe items for encapsulation encapsulating the ICs at the processing position.

2. (Currently Amended) The [[A]] method according to claim 1 in which the at least two plurality of holders are portions of a single member, the step of moving the holders being a motion of the member.

3. (Currently Amended) The [[A]] method according to claim 2, in which the motion is a reciprocating motion and the processing region is located between the at least two reception positions.

4. (Currently Amended) The [[A]] method according to claim 3 in which the at least two reception positions are respectively above and below the processing region.

5. (Currently Amended) The [[A]] method according to claim 1 in which the leadframe items are provided in corresponding magazines, the holders receiving the leadframe items within the corresponding magazines, and the method further including extracting the leadframe items from the magazines in the processing region

6. (Withdrawn) An apparatus for processing leadframe items to form IC packages, each of the leadframe items comprising an IC carried by a suitable leadframe, the leadframe items being of two or more types, the apparatus including:

a loading device comprising:

at least two conveyors arranged to convey the respect types of leadframe items along respective input paths;

at least two holders;

an actuator for moving the multiple holders alternately between a processing region and a respective leadframe item reception position, the reception positions being on respective ones of the input paths, and each of the holders being arranged to receive leadframe items of the respective type at the respective reception position and deliver them to the processing region; and

an encapsulating device at the processing position for encapsulating the ICs.

7. (Withdrawn) A loading device for use in the apparatus of claim 6.